SOT500-3

plastic leadless module carrier package; 35 mm wide tape

8 February 2016 Package information

1. Package summary

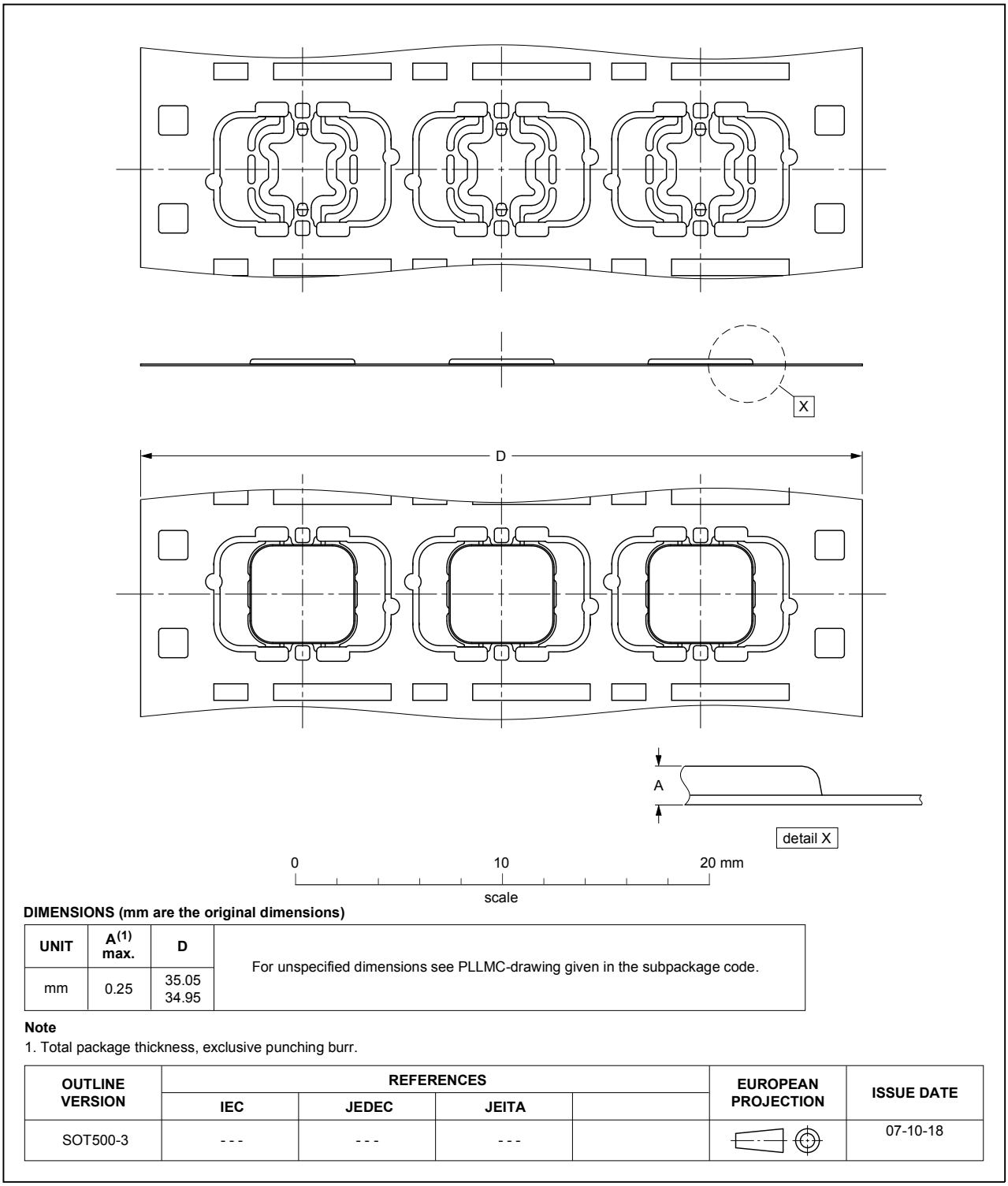
Terminal position code	B (bottom)
Package type descriptive code	PLLMC
Package type industry code	PLLMC
Package style descriptive code	PLLMC (plastic leadless module carrier)
Package style suffix code	NA (not applicable)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	18-10-2007

Table 1. Package summary

Symbol	Parameter		Min	Typ	Nom	Max	Unit
D	package length		[tbd]	-	35	[tbd]	mm
A	seated height		[tbd]	-	0.25	0.25	mm
n_2	actual quantity of termination		-	-	0	-	

2. Package outline

PLLMC: plastic leadless module carrier package; 35 mm wide tape **SOT500-3**



DIMENSIONS (mm are the original dimensions)

UNIT	A(1) max.	D	
mm	0.25	35.05 34.95	For unspecified dimensions see PLLMC-drawing given in the subpackage code.

Note

1. Total package thickness, exclusive punching burr.

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT500-3	- - -	- - -	- - -			07-10-18

Fig. 1. Package outline PLLMC (SOT500-3)

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4. Contents

1. Package summary..... 1
2. Package outline..... 2
3. Legal information..... 3

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